

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A ~~metal polishing pad~~ for polishing metal having a functional group which captures a metal ion, wherein the metal polishing pad comprises at least one member selected from the group consisting of functional group containing chelate resin and functional group containing chelate fiber, and the functional group of the chelate resin or chelate fiber is at least one member selected from the group consisting of aminocarboxylic acid, aminophosphonic acid and imino diacetic acid.

2. - 5. (Cancelled)

6. (Original) The polishing pad according to Claim 1, wherein the metal is a copper-based metal.

7. (Currently Amended) A metal polishing apparatus comprising a metal polishing pad according to Claim 1, operatively connected to a movable pad support for supporting the metal polishing pad, and a polishing subject having a metal layer for polishing, wherein the polishing subject is operatively connected to a movable subject support for supporting the polishing subject.

8. (Currently Amended) A polishing apparatus comprising ~~an apparatus of~~ a means for contacting a polishing subject having a metal surface with a confronting polishing pad according to Claim 1 and applying pressure uniformly between ~~them, an apparatus of the~~ polishing subject and the polishing pad; a means for rotating or transferring ~~a the~~ the polishing subject and ~~a~~ a polishing pad while maintaining contact ~~between them, therebetween;~~ and ~~an apparatus of~~ a means for feeding a polish promoting agent ~~for promoting to~~ promote polishing ~~into~~ between ~~a~~ the polishing subject and ~~a~~ a polishing pad.

9. (Original) The polishing apparatus according to Claim 8, wherein the polish promoting agent contains an oxidizer.

10. (Currently Amended) The polishing apparatus according to Claim 7 further comprising a functional group regeneration ~~treatment apparatus means for~~ of contacting the polishing pad with a regenerating agent which regenerates ~~a functional group~~ groups deactivated by capturing a metal ~~with a polishing pad according to~~ Claim 1 after polishing a polishing subject.

11. (Currently Amended) The polishing apparatus according to Claim 10, wherein the regenerating agent is an acidic aqueous solution or an alkaline aqueous solution.

12. (Currently Amended) The polishing apparatus according to Claim 7, wherein the metal is a copper-based metal.

13. (Cancelled)

14. (Currently Amended) A method for polishing a metal comprising the steps of

rotating or transferring a polishing pad according to Claim 1, a polishing subject having a metal surface, or both ~~of them~~ while maintaining prescribed contact therebetween ~~keeping the condition of the polishing pad according to Claim 1 pushed to the polishing subject having a metal surface,~~ and

feeding a polish promoting agent between the metal surface and polishing pad.

15. (Currently Amended) The method according to Claim 14, wherein the polishing pad is a pad regenerated by a functional group regeneration ~~treatment apparatus according to Claim 10~~ means

for contacting the polishing pad with a regenerating agent which regenerates a functional groups deactivated by capturing a metal after polishing a polishing subject.

16. (Original) The polishing method according to Claim 13, wherein the metal is a copper-based metal.

17. (New) The polishing pad according to Claim 1, wherein the functional group is aminocarboxylic acid.

18. (New) The polishing pad according to Claim 1, wherein the functional group is aminophosphonic acid.

19. (New) The polishing pad according to Claim 1, wherein the functional group is imino diacetic acid.